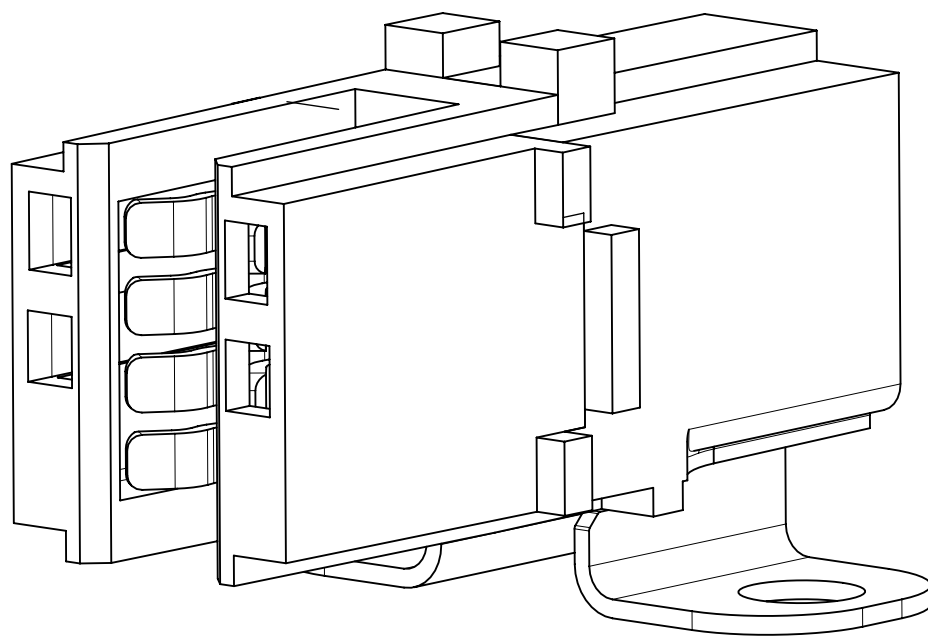
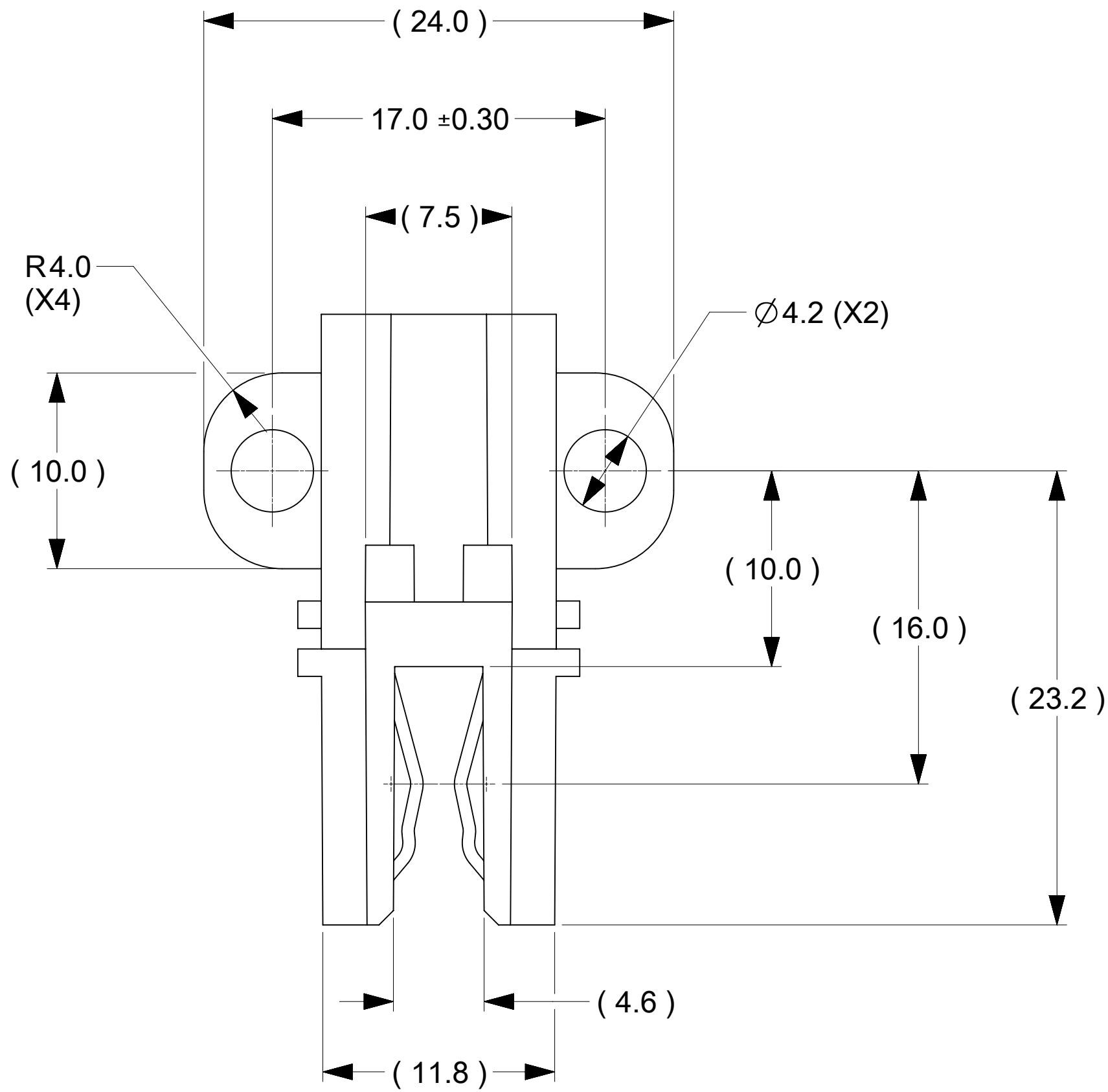
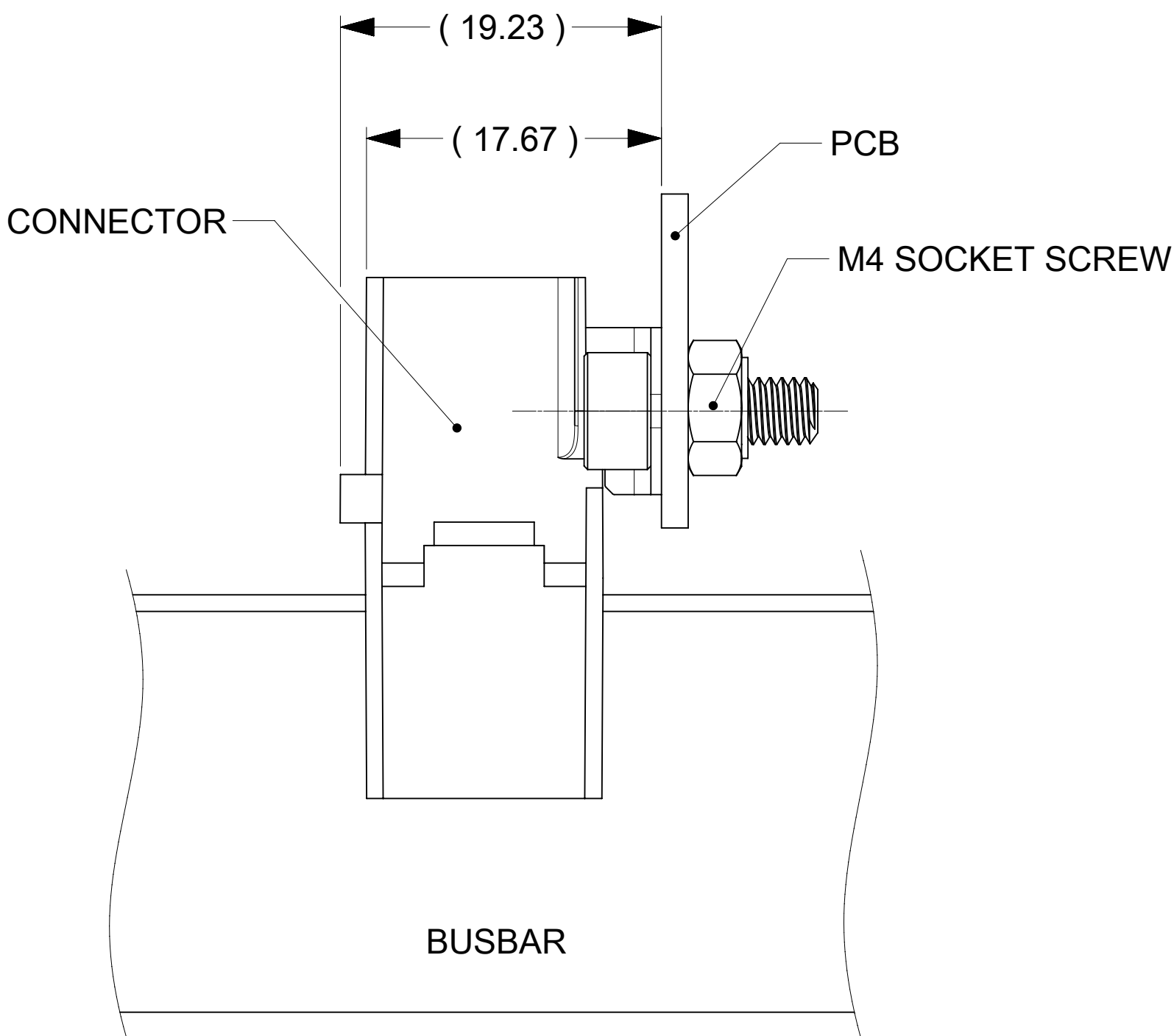
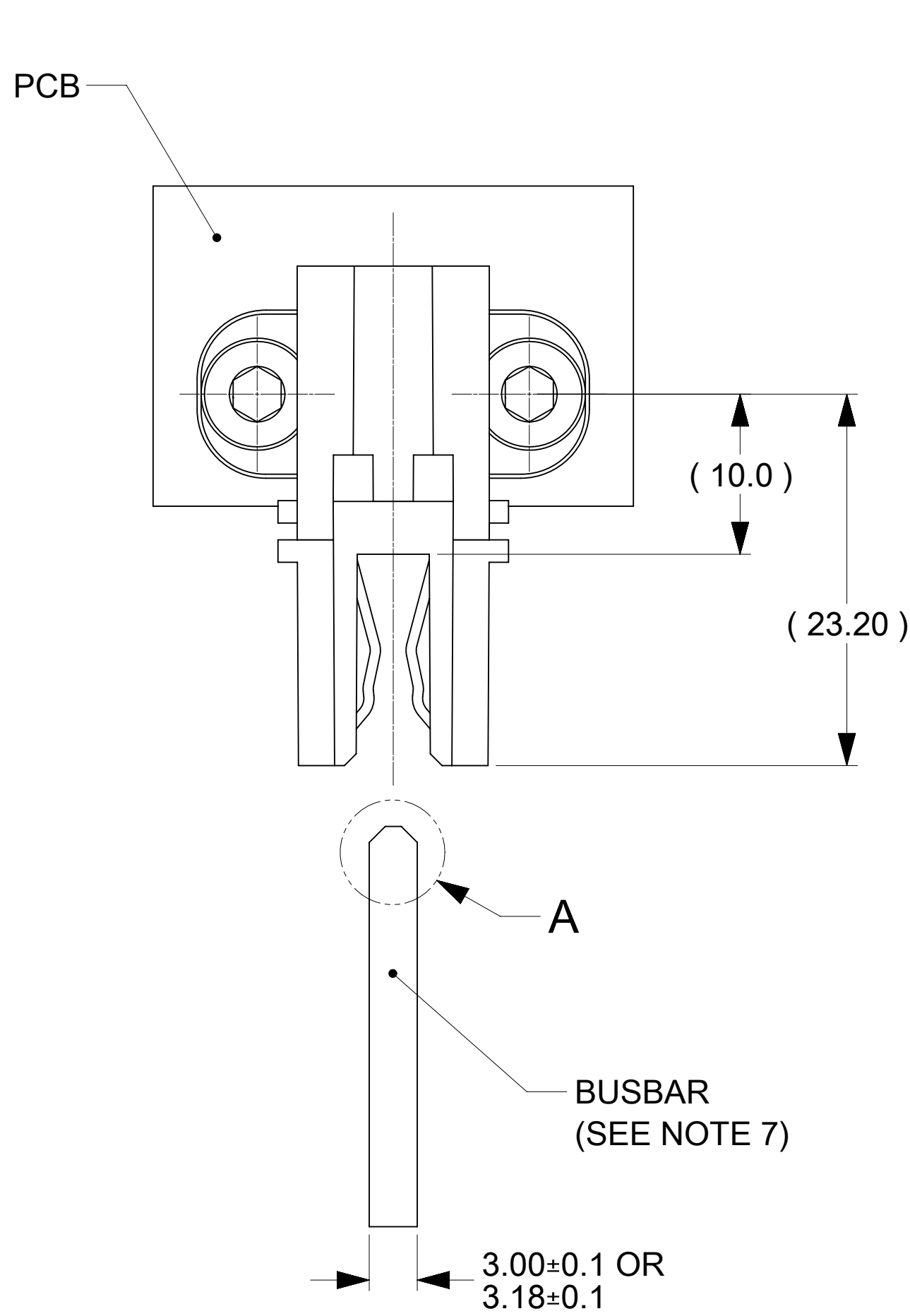
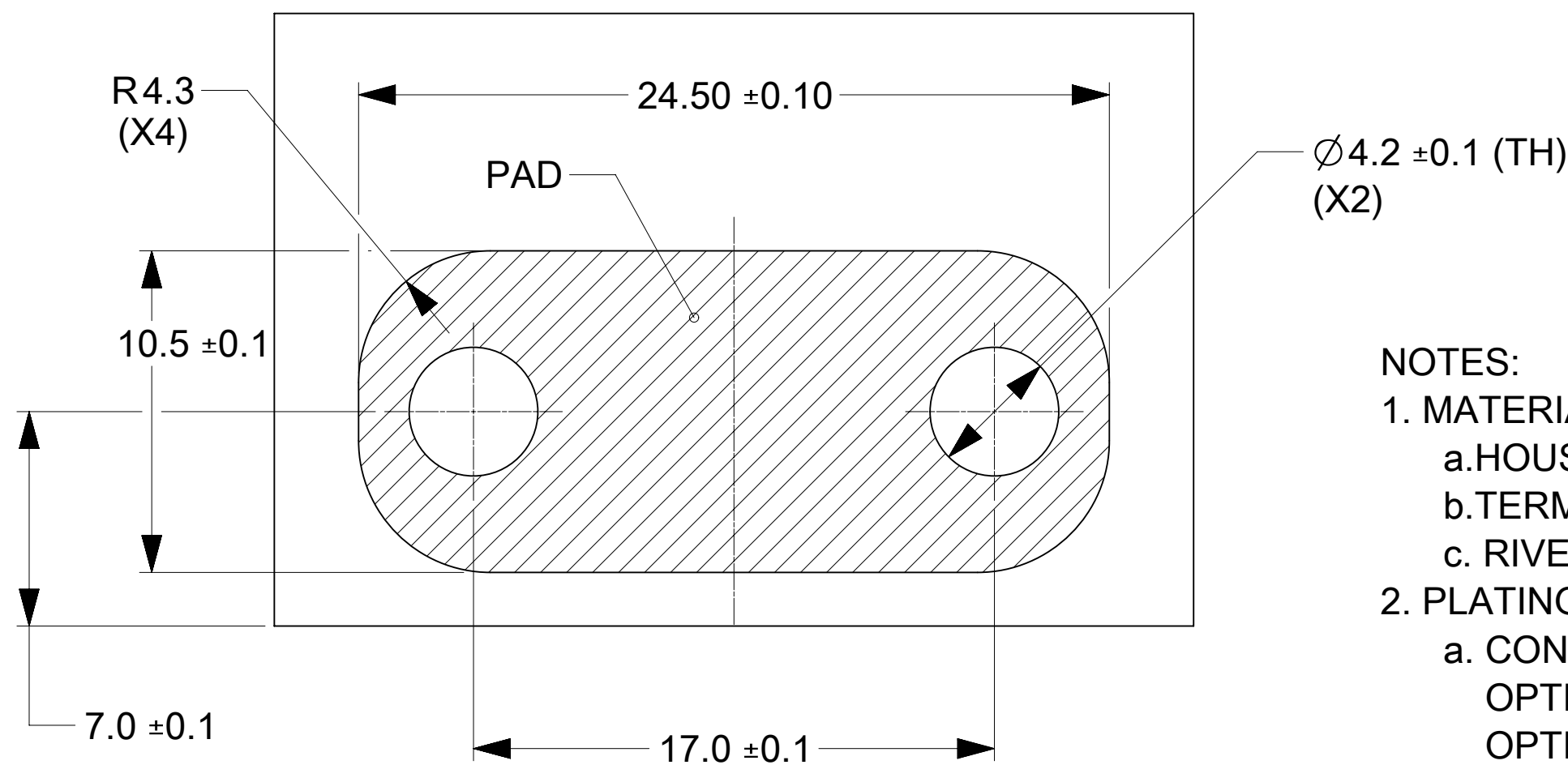




PCB, BUSBAR, SCREWS AND NUTS
IN THESE VIEWS ARE SHOWN FOR REFERENCE ONLY



RECOMMENDED PCB LAYOUT

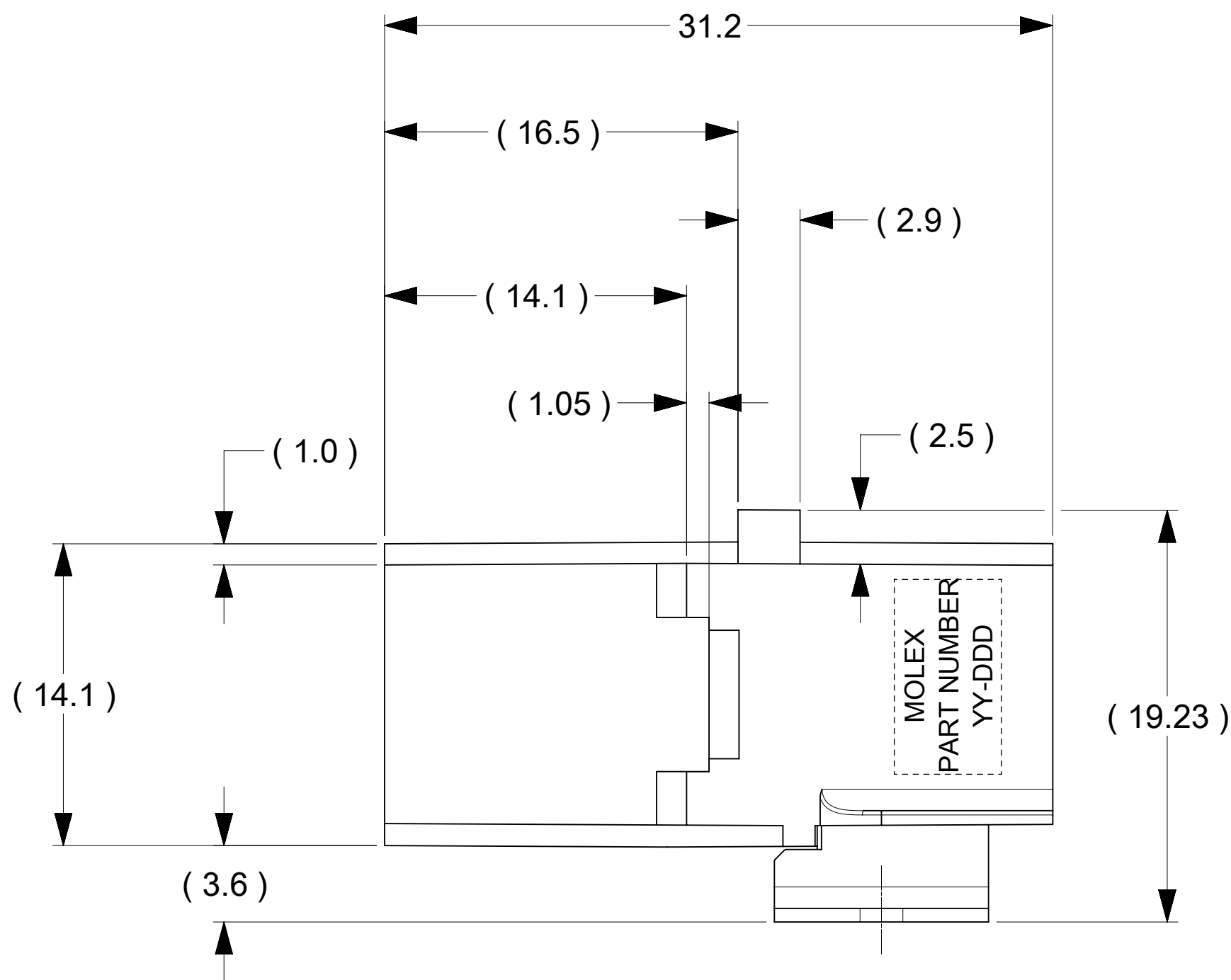
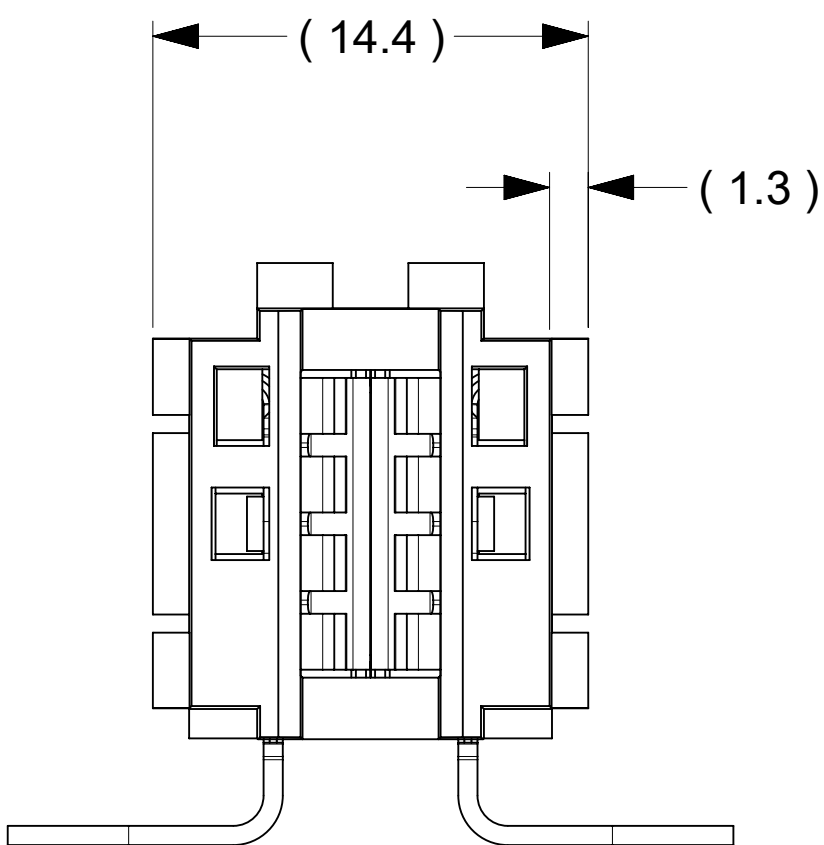
0.5 MIN. CHAMFERED
EDGE RECOMMENDED

DETAIL A
SCALE 10:1

NOTES:

- MATERIALS:
 - HOUSING BODY: POLYMER. UL94V-0; BLACK.
 - TERMINALS: COPPER ALLOY.
 - RIVET/CLIP: COPPER ALLOY.
- PLATING:
 - CONTACT AREAS:
 - OPTION 1: 3.18 MICRON MIN. SILVER, OVER 1.27 MICRON MIN. NICKEL.
 - OPTION 2: 2.50 MICRON MIN. MATTE TIN OV34 1.27 MICRON MIN. NICKEL
 - TAB AREAS: 3.18 MICRON MIN. TIN OVER 1.27 MICRON MIN. NICKEL.
 - REST: 1.27 MICRON MIN. NICKEL.
- LUBRICATION: LUBED IN CONTACT AREA.
- REFERENCE DOCUMENT:
 - SILVER VERSION: 2131910001-PS, 2131910001-AS.
 - TIN VERSION: 2131910002-PS, 2131910001-AS.
- MODULE ASSEMBLY IS RoHS COMPLIANT.
- FINAL ASSEMBLY TO BE PACKAGED AND LABELED PER PACKAGING DRAWING NUMBER 2131910002-PK.
- MATED BUSBAR SHOULD BE PLATED WITH SILVER OVER NICKEL FOR SILVER VERSION CONNECTOR AND TIN OVER NICKEL FOR TIN VERSION CONNECTOR.

PART NUMBER	PLATING ON THE CONTACT AREAS
213191-0002	SILVER OVER NICKEL
213191-0102	TIN OVER NICKEL



FUNCTIONAL SYMBOLS	THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX ELECTRONIC TECHNOLOGIES, LLC AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION									
	DIMENSION UNITS		SCALE		CURRENT REV DESC:		molex			
F_A = 0	mm	5:1								
F_C = 0	GENERAL TOLERANCES (UNLESS SPECIFIED)			POWER PLANE BBC SMALL RA - SM						
F_P = 0	ANGULAR TOL ± °									
DIVISIONAL SYMBOLS	4 PLACES		±		EC NO: 783826		PRODUCT CUSTOMER DRAWING			
	3 PLACES		±		DRWN: JOEJ3					